SDF5050AB-1 Epoxy Resin
Technical datasheet

Description & Application

SDF5050AB-1 is an epoxy resin black encapsulant cured at room temperature and low temperature, good fluidity, natural defoaming, room temperature curing or heating and curing. Dedicated to the machine pouring of electronic components potting, power packaging, mold infusion and other electronic parts of the insulation, moisture potting, confidentiality, etc.

Product data

	SDF5050A-1	SDF5050B-1	Mixed Adhesive
Appearance	*Black*	*Red Black*	
Specific gravity	*1.65*	*0.96*	
Viscosity at 25°C (Pa.s)	*1500-4000*	*500-2000*	*1000-1500*
Mixing Ratio (weight)	*100*	*20*	
Pot life at 25°C (100gr)			*45min*
Curing Conditions (2gr)			*8-10h at* 25°C *2h at* 55°C

Processing

Working environment: Please keep the plastic container clean. A, B components are strictly according to the weight ratio, accurately weighed, and stir it evenly along the inner wall of the container clockwise until it is used for 3-5 minutes.
According to the operating time and amount of glue deployment, to avoid waste.
When the temperature is lower than 15 °C, please pre-heat the A glue to 30 °C and then adjust the rubber, easy to operate (low temperature, A glue will thicken); After use must seal the lid, to avoid the product due to moisture absorption scrapped.
When the relative humidity is more than 85%, the surface of the cured product can easily absorb the moisture in the air to form a white mist. Therefore, when the relative humidity is more than 85%, it is not suitable for room temperature curing. It is recommended to use the heating and curing.
The lid must be sealed after use to avoid the product being scrapped due to moisture absorption.

Typical cured properties

Hardness	*Shore D*	78-83
Withstand voltage	*KV/mm*	22
Bending strength	*Kg/mm2*	23
Volume resistance	*Ohm3*	1x10*15
Surface resistance	*Ohmm2*	5x10*15
Thermal conductivity	*W/M.K*	0.60
Lure power loss	*1KHZ*	0.42
Working Temperature Range	*℃*	*-50 ～ 140*
Water absorption	*%*	<0.15
Compressive strength	*Kg/mm2*	11.3

The above performance data are typical data measured in a laboratory environment with a temperature of 25 ° C and a humidity of 70%, and are for customer reference only.